

**Listing of Claims**

This listing of claims will replace all prior versions, and listings, of claims in the application:

Please cancel claims 1-65 without prejudice or disclaimer.

Please add the following new claims:

66. (New) A semiconductor device comprising:

a semiconductor chip comprising a bump disposed on the semiconductor chip for being bonded to a control terminal;

first and second radiation members thermally and electrically connected to the semiconductor chip interposed therebetween, and having a radiation surface for radiating heat from the semiconductor chip; and

first and second bonding members respectively interposed between the first radiation member and the semiconductor chip and between the semiconductor chip and the second radiation member, wherein:

the first and second radiation members are made of a metallic material that is superior to tungsten and molybdenum in at least one of an electrical conductivity and a thermal conductivity.

67. (New) The semiconductor device of claim 66, wherein no wire is required to be bonded from the control terminal to the semiconductor chip for providing electrical communication with an external device.